



1. Plating Thickness	Electro Nickel Ni: 1.27 – 8.89 micron (Solder Pads) Electro Gold Au: 0.70-1.20 micron (Solder Pads)
2. Connection	1-3-GND-D/A-S/R, 2-OE, 4-Out, 5-OutN, 6-7-VCC, 8-XIN, 10-A-B-D 11-VC XR-C-B, 9-NC
3. Camber	50.00 micron maximum
Exposure of ceramic surface occurring by misalignment of the upper layer shall be allowed.	
■ indicates the side metalized pattern	
Stress Relaxation design shall be applied on this item	
Sealing Method of this product shall be seam weld.	

Type	Sub-type	Description		S5070VCX03
Design	Check	Approved	Rev.	
AB	ER	TH	A	
				<b>VC</b> America

11/3/07